

ABSTRACT OF THE DISCLOSURE

The invention provides a method for manufacturing a piezoelectric element including a coating step of coating a substrate with a coating liquid for forming the piezoelectric element thereby forming a coated film, a drying step of drying the coated film, a preliminary sintering step of preliminarily sintering the coated film thereby forming an oxide film, a final sintering step of finally sintering the oxide film thereby forming a piezoelectric film, and a cooling step of cooling the piezoelectric film, wherein the steps are executed in the presence of a moisture-containing gas; in the coating step the substrate has a temperature equal to or less than 50°C and the moisture-containing gas has a relative humidity of 60 %RH or less at 25°C; in the drying step, the substrate has a temperature equal to or less than 200°C and the relative humidity is 10 to 70 %RH; in the preliminary sintering step the substrate has a temperature of 200 to 450°C and the relative humidity is 70 to 100 %RH; in the final sintering step the substrate has a temperature of 500 to 800°C and the relative humidity is 70 to 100 %RH.